

Is Now Part of



ON Semiconductor®

To learn more about ON Semiconductor, please visit our website at www.onsemi.com

Please note: As part of the Fairchild Semiconductor integration, some of the Fairchild orderable part numbers will need to change in order to meet ON Semiconductor's system requirements. Since the ON Semiconductor product management systems do not have the ability to manage part nomenclature that utilizes an underscore (_), the underscore (_) in the Fairchild part numbers will be changed to a dash (-). This document may contain device numbers with an underscore (_). Please check the ON Semiconductor website to verify the updated device numbers. The most current and up-to-date ordering information can be found at www.onsemi.com. Please email any questions regarding the system integration to Fairchild guestions@onsemi.com.

ON Semiconductor and the ON Semiconductor logo are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any EDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold ON Semiconductor and its officer



FDMS8026S

October 2014

N-Channel PowerTrench[®] SyncFETTM 30 V, 22 A, 4.3 m Ω

Features

- Max $r_{DS(on)} = 4.3 \text{ m}\Omega$ at $V_{GS} = 10 \text{ V}$, $I_D = 19 \text{ A}$
- Max $r_{DS(on)} = 5.2 \text{ m}\Omega$ at $V_{GS} = 4.5 \text{ V}$, $I_D = 17 \text{ A}$
- Advanced package and Silicon combination for low r_{DS(on)} and high efficiency
- SyncFET Schottky Body Diode
- MSL1 robust package design
- 100% UIL tested
- RoHS Compliant

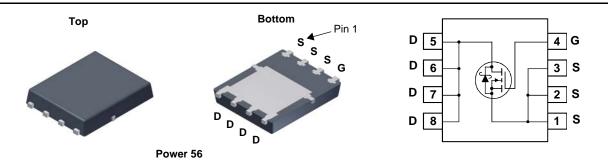


General Description

The FDMS8026S has been designed to minimize losses in power conversion application. Advancements in both silicon and package technologies have been combined to offer the lowest $r_{\text{DS}(\text{on})}$ while maintaining excellent switching performance. This device has the added benefit of an efficient monolithic Schottky body diode.

Applications

- Synchronous Rectifier for DC/DC Converters
- Notebook Vcore/GPU low side switch
- Networking Point of Load low side switch
- Telecom secondary side rectification



MOSFET Maximum Ratings T_A= 25°C unless otherwise noted

Symbol	Parameter			Ratings	Units
V _{DS}	Drain to Source Voltage			30	V
V _{GS}	Gate to Source Voltage		(Note 4)	±20	V
	Drain Current -Continuous (Package limited)	T _C = 25°C		22	
	-Continuous (Silicon limited)	T _C = 25°C		80	^
ID	-Continuous	T _A = 25°C	(Note 1a)	19	Α
	-Pulsed			100	
E _{AS}	Single Pulse Avalanche Energy		(Note 3)	33	mJ
P_{D}	Power Dissipation	T _C = 25°C		41	W
	Power Dissipation $T_A = 25^{\circ}C$ (Note 1a)		(Note 1a)	2.5	VV
T _J , T _{STG}	Operating and Storage Junction Temperature R	ange		-55 to +150	°C

Thermal Characteristics

F	$R_{\theta JC}$	Thermal Resistance, Junction to Case		3.0	°C/W
F	Raia	Thermal Resistance, Junction to Ambient (N	Note 1a)	50	C/VV

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDMS8026S	FDMS8026S	Power 56	13 "	12 mm	3000 units

Electrical Characteristics $T_J = 25$ °C unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Chara	cteristics					
BV_{DSS}	Drain to Source Breakdown Voltage	$I_D = 1$ mA, $V_{GS} = 0$ V	30			V
$\frac{\Delta BV_{DSS}}{\Delta T_{J}}$	Breakdown Voltage Temperature Coefficient	I _D = 10 mA, referenced to 25°C		23		mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 24 V, V _{GS} = 0 V			500	μΑ
I _{GSS}	Gate to Source Leakage Current, Forward	V _{GS} = 20 V, V _{DS} = 0 V			100	nA

On Characteristics

V _{GS(th)}	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}$, $I_D = 1$ mA	1.2	1.5	3.0	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	I _D = 10 mA, referenced to 25°C		-4		mV/°C
	Static Drain to Source On Resistance	V _{GS} = 10 V, I _D = 19 A		3.6	4.3	
r _{DS(on)}		$V_{GS} = 4.5 \text{ V, } I_D = 17 \text{ A}$		4.5	5.2	mΩ
		V _{GS} = 10 V, I _D = 19 A, T _J = 125°C		4.8	6.0	
g _{FS}	Forward Transconductance	V _{DS} = 5 V, I _D = 19 A		103		S

Dynamic Characteristics

C _{iss}	Input Capacitance	V - 15 V V - 0 V	1715	2280	pF
C _{oss}	Output Capacitance	$V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V},$ $f = 1MHz$	655	870	pF
C _{rss}	Reverse Transfer Capacitance	1 = 11/1112	75	110	pF
R_g	Gate Resistance		0.7	2.5	Ω

Switching Characteristics

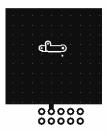
t _{d(on)}	Turn-On Delay Time		9.0	18	ns
t _r	Rise Time	V _{DD} = 15 V, I _D = 19 A,	3.9	10	ns
t _{d(off)}	Turn-Off Delay Time	$V_{GS} = 10 \text{ V}, R_{GEN} = 6 \Omega$	25	40	ns
t _f	Fall Time		3.2	10	ns
Q_g	Total Gate Charge	V _{GS} = 0 V to 10 V	27	37	nC
Qg	Total Gate Charge	$V_{GS} = 0 \text{ V to } 4.5 \text{ V}$ $V_{DD} = 15 \text{ V}$	13	19	nC
Q _{gs}	Gate to Source Charge	I _D = 19 A	4.2		nC
Q _{gd}	Gate to Drain "Miller" Charge		3.7		nC

Drain-Source Diode Characteristics

V _{SD}	I Source-Drain Dioge Forward Voltage	$V_{GS} = 0 \text{ V, } I_S = 2 \text{ A}$ (Note 2)	0.6	0.8	V
		$V_{GS} = 0 \text{ V, } I_S = 19 \text{ A}$ (Note 2)	8.0	1.2	
t _{rr}	Reverse Recovery Time	I _F = 19 A, di/dt = 300 A/μs	24	38	ns
Q _{rr}	Reverse Recovery Charge	TF = 19 A, α/αι = 300 A/μs	24	38	nC

Notes:

^{1.} R_{0,DA} is determined with the device mounted on a 1 in² pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material. R_{0,JC} is guaranteed by design while R_{0CA} is determined by the user's board design.



a. 50 °C/W when mounted on a
 1 in² pad of 2 oz copper.



 b. 125 °C/W when mounted on a minimum pad of 2 oz copper.

- 2. Pulse Test: Pulse Width < 300 $\mu\text{s},$ Duty cycle < 2.0%.
- 3. E_{AS} of 33 mJ is based on starting T_J = 25 °C, L = 0.3 mH, I_{AS} = 15 A, V_{DD} = 27 V, V_{GS} = 10 V.
- 4. As an N-ch device, the negative Vgs rating is for low duty cycle pulse occurrence only. No continuous rating is implied.

Typical Characteristics $T_J = 25$ °C unless otherwise noted

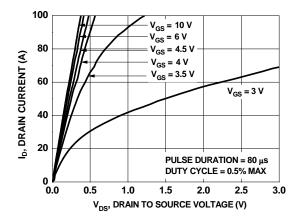


Figure 1. On Region Characteristics

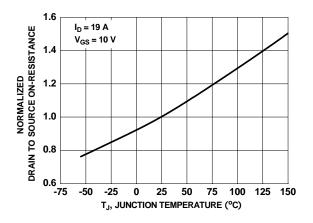


Figure 3. Normalized On Resistance vs Junction Temperature

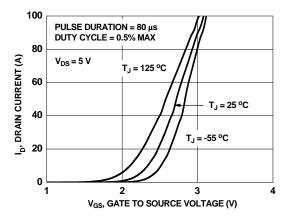


Figure 5. Transfer Characteristics

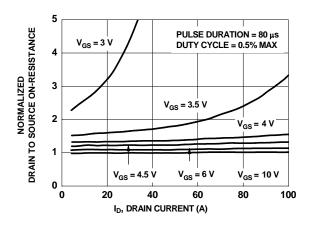


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

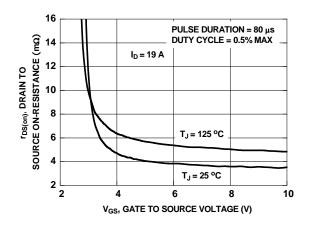


Figure 4. On-Resistance vs Gate to Source Voltage

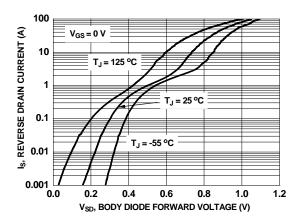


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

Typical Characteristics T_J = 25°C unless otherwise noted

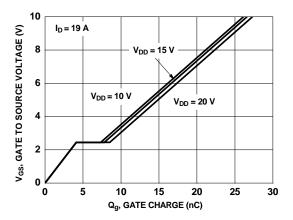


Figure 7. Gate Charge Characteristics

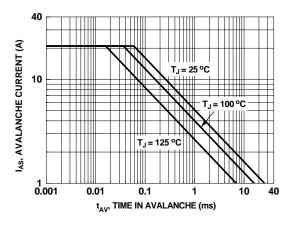


Figure 9. Unclamped Inductive Switching Capability

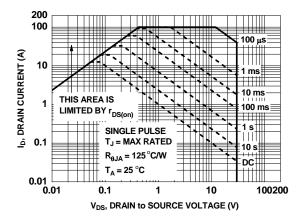


Figure 11. Forward Bias Safe Operating Area

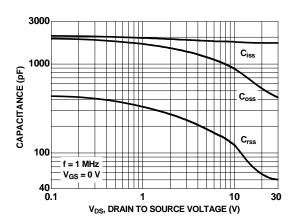


Figure 8. Capacitance vs Drain to Source Voltage

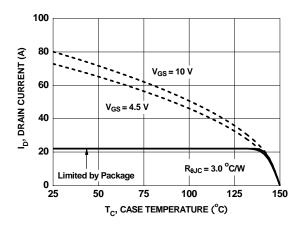


Figure 10. Maximum Continuous Drain Current vs Case Temperature

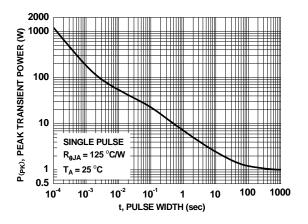


Figure 12. Single Pulse Maximum Power Dissipation

Typical Characteristics $T_J = 25$ °C unless otherwise noted

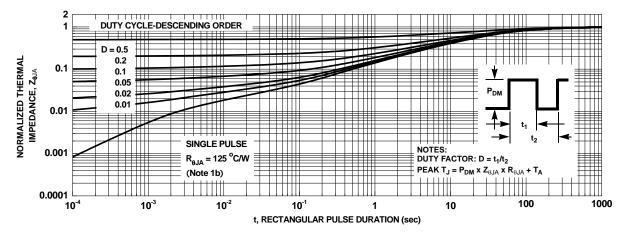


Figure 13. Junction-to-Ambient Transient Thermal Response Curve

Typical Characteristics (continued)

SyncFET Schottky body diode Characteristics

Fairchild's SyncFET process embeds a Schottky diode in parallel with PowerTrench MOSFET. This diode exhibits similar characteristics to a discrete external Schottky diode in parallel with a MOSFET. Figure 14 shows the reverse recovery characteristic of the FDMS8026S.

Schottky barrier diodes exhibit significant leakage at high temperature and high reverse voltage. This will increase the power in the device.

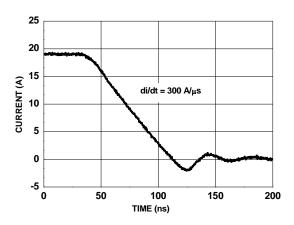


Figure 14. FDMS8026S SyncFET body diode reverse recovery characteristic

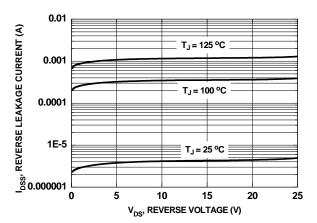
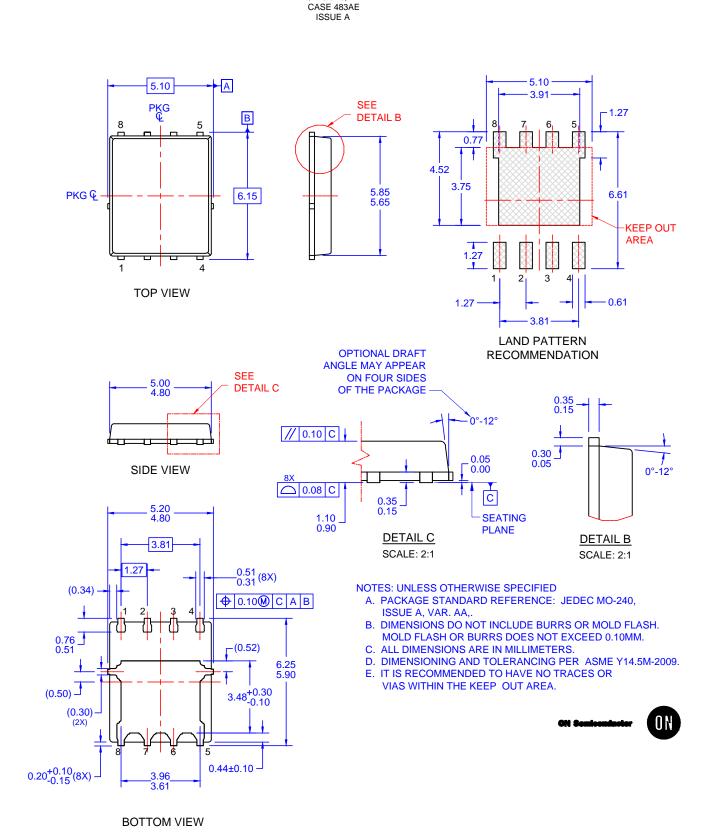


Figure 15. SyncFET body diode reverse leakage versus drain-source voltage



ON Semiconductor and in are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at www.onsemi.com/site/pdt/Patent-Marking.pdf. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold ON Semiconductor and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and exp

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor 19521 E. 32nd Pkwy, Aurora, Colorado 80011 USA Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada Email: orderlit@onsemi.com N. American Technical Support: 800-282-9855 Toll Free USA/Canada
Europe, Middle East and Africa Technical Support:
Phone: 421 33 790 2910
Japan Customer Focus Center
Phone: 81-3-5817-1050

ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

ON Semiconductor: FDMS8026S